MLCAD 2019 - 1st ACM/IEEE Workshop on Machine Learning for CAD, September 3-4, 2019 @ Banff Area, Canada

Call for Abstracts / Call for Participation

MLCAD Workshop
This workshop focuses on Machine Learning (ML) methods for all aspects of CAD and electronic system design. The predecessor of this workshop was held at the Design, Automation and Test in Europe (DATE) Conference in March 2019. The workshop is sponsored by both IEEE Council on Electronic Design Automation (CEDA) and ACM Special Interest Group on Design Automation (SIGDA). Around one third of the workshop program will consist of invited and keynote speakers from major CAD and Industrial Companies, who will present their vision on machine learning for CAD.

Two Ways to Attend:
1. Presenter: Submit a half page abstract (~500 words incl. title and authors and submit PDF to https://easychair.org/conferences/?conf=mlcad2019. Accepted submissions entitle to a talk at the workshop and a full paper submission to the 1st ACM/IEEE Workshop on MLCAD post workshop proceedings (for full info check mlcad.itec.kit.edu).
2. Attendee: We encourage senior researchers as well as PhD students to be part of this first workshop. Participation is limited to maintain the creative open discussion atmosphere of the workshop. Registration deadline is July 22nd 2019. Registration will be handled on a first-come, first-serve basis.

Post-Workshop Proceedings
Formal shared ACM/IEEE proceedings will be published after the workshop. All speakers are invited to submit full papers about two months after the workshop.

Venue
MLCAD 2019 is held at the Solara Resort & Spa, which is located in Canmore, (Banff area), Alberta, Canada. The location is near to the Canadian Rocky Mountains and the beautiful Banff National Park of Canada. The location is reachable with flights to Calgary International Airport (YYC), which is about one hour drive away.

Exemplary topics of interest:
1. ML approaches to logic design
2. ML for physical design
3. ML for analog design
4. ML methods to predict aging and reliability
5. Labeled and unlabeled data in ML for CAD
6. ML for power and thermal management
7. ML techniques for resource management in many cores
8. ML for Design Technology Co-Optimization (DTCO)

General Chairs
Marilyn Wolf, Georgia Institute of Technology
Jörg Henkel, Karlsruhe Institute of Technology

Industry Chairs
Ulf Schlichtmann, TU Munich
Paul Franzon, North Carolina State U.

Program Chairs
Hussam Amrouch, Karlsruhe Institute of Technology
Bei Yu, Chinese University of Hong Kong

Finance Chair
Hai Li, Duke University

Abstract Submission: July 7, 2019
Author Notification: July 15, 2019
Registration Deadline: July 22, 2019
Workshop: September 3-4, 2019

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